

## 650V 7A N-Channel Enhancement Mode Power MOSFET

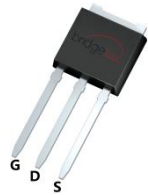
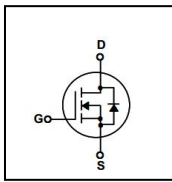
### General Description

BXP7N65 is Bridgelux high voltage MOSFET family based on advanced planar stripe DMOS technology. This advanced MOSFET family has optimized on-state resistance, and also provides superior switching performance and higher avalanche energy strength. This device family is suitable for high efficiency switch mode power supplies.

### FEATURES

- $R_{DS(ON)} \leq 1.4 \Omega$  @  $V_{GS}=10V, I_D=3.5A$
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Fast switching capability
- Lead free product is acquired

### SYMBOL



TO-251L



TO-252



TO-220



TO-220F

### ASSEMBLY MESSAGE

Product Name	Marking	Package	Packaging
BXP7N65U	BXP7N65U	TO-251L	Tube
BXP7N65D	BXP7N65D	TO-252	Tube/Reel
BXP7N65P	BXP7N65P	TO-220	Tube
BXP7N65CF	BXP7N65C	TO-220F	Tube

### ABSOLUTE MAXIMUM RATINGS ( $T_C=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Rating			Unit
		BXP7N65U/D	BXP7N65P	BXP7N65CF	
Drain-Source Voltage	$V_{DSS}$	650			V
Drain Current	Continuous ( $T_C = 25^\circ C$ )	7			A
	Continuous ( $T_C = 100^\circ C$ )	3.9			A
Drain Current	Pulsed (Note1)	28			A
Gate-Source Voltage	$V_{GSS}$	$\pm 30$			V
Avalanche Energy	Single Pulse (Note2)	450			mJ
	Repetitive (Note1)	21			mJ
Avalanche Current (Note1)	$I_{AR}$	7			A
Peak Diode Recovery dv/dt (Note3)	dv/dt	4.6			V/ns
Power Dissipation (Note 2)	$T_C = 25^\circ C$	145	167	46	W
	Derate above $25^\circ C$	1.16	1.34	0.37	W/ $^\circ C$
Maximum Junction Temperature	$T_J$	150			$^\circ C$
Storage Temperature Range	$T_{STG}$	-55 to 150			$^\circ C$

- Note:
1. Repetitive Rating: Pulse width limited by maximum junction temperature
  2.  $L=18mH, V_{DD}=50V, R_G=25 \Omega$ , Starting  $T_J = 25^\circ C$
  3.  $I_{SD} \leq 7.0A, di/dt \leq 300A/\mu s, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ C$

**THERMAL CHARACTERISTICS**

Parameter	Symbol	Max.			Unit
		BXP7N65U/D	BXP7N65P	BXP7N65CF	
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.86	0.75	2.72	°C / W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	62.5	120	°C / W

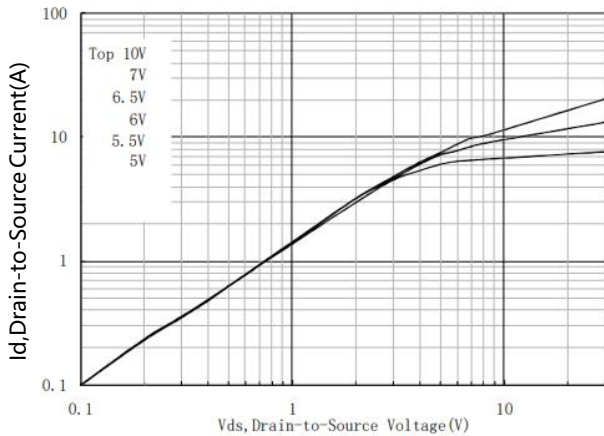
**ELECTRICAL CHARACTERISTICS** ( $T_J=25^\circ\text{C}$ , unless otherwise Noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	650			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=650V, V_{GS}=0V$			1	$\mu A$
		$V_{DS}=520V, T_C = 125^\circ\text{C}$			100	$\mu A$
Gate-Body Leakage Current, Forward	$I_{GSS}$	$V_{GS}=30V$			100	nA
Gate-Body Leakage Current, Reverse		$V_{GS}=-30V$			-100	nA
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	$I_D = 250 \mu A$		0.62		$V/^\circ\text{C}$
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2		4	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=3.5A$		1.17	1.4	$\Omega$
Forward Transconductance (Note4)	$g_{FS}$	$V_{DS} = 50V, I_D = 3.5A$		3.2		S
<b>DYNAMIC PARAMETERS</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=25V, V_{GS}=0V,$ $f=1.0\text{MHz}$		970		pF
Output Capacitance	$C_{OSS}$			90		pF
Reverse Transfer Capacitance	$C_{RSS}$			8.3		pF
<b>SWITCHING PARAMETERS</b>						
Turn-ON Delay Time	$t_{D(ON)}$	$V_{DD}=325V, I_D=7A, V_{GS} = 10V, R_G=10\Omega$ (Note4,5)		24		ns
Turn-ON Rise Time	$t_R$			16		ns
Turn-OFF Delay Time	$t_{D(OFF)}$			40		ns
Turn-OFF Fall-Time	$t_F$			15.7		ns
Total Gate Charge(Note5)	$Q_G$	$V_{DS} = 520V, V_{GS} = 10V, I_D = 7A$ (Note4,5)		21		nC
Gate Source Charge	$Q_{GS}$			5.6		nC
Gate Drain Charge	$Q_{GD}$			9		nC
<b>SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS</b>						
Drain-Source Diode Forward Voltage	$V_{SD}$	$I_S=7A, V_{GS}=0V$			1.4	V
Diode Continuous Forward Current	$I_S$				7	A
Pulsed Drain-Source Current	$I_{SM}$				28	A
Reverse Recovery Time	$t_{RR}$	$V_{GS} = 0V, I_{SD} = 7A$		320		ns
Reverse Recovery Charge	$Q_{RR}$	$di/dt=100A/\mu s$ (Note4,5)		2.9		$\mu C$

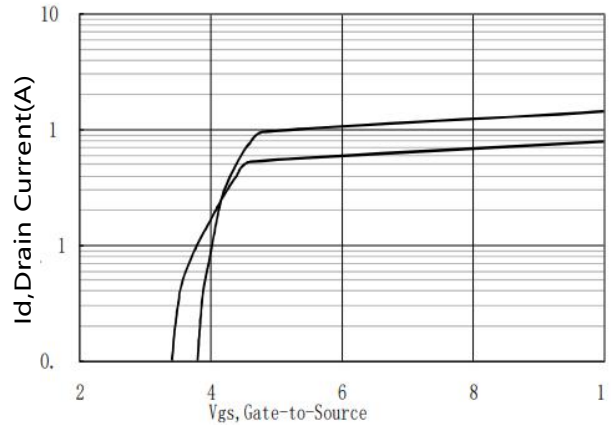
Note: 4. Pulse Test : Pulse width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$

5. Essentially independent of operating temperature

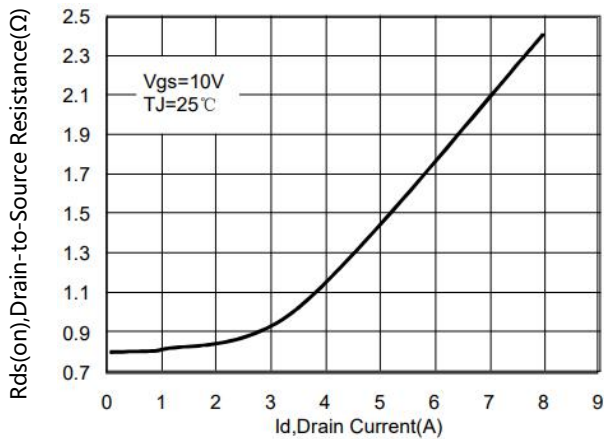
**TYPICAL CHARACTERISTICS**



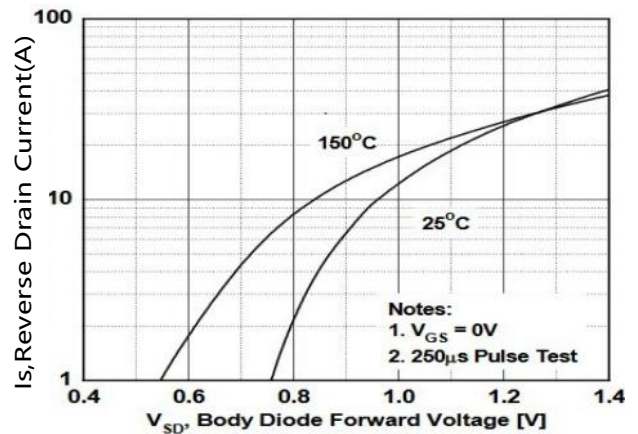
**Figure1. Typical Output Characteristics**



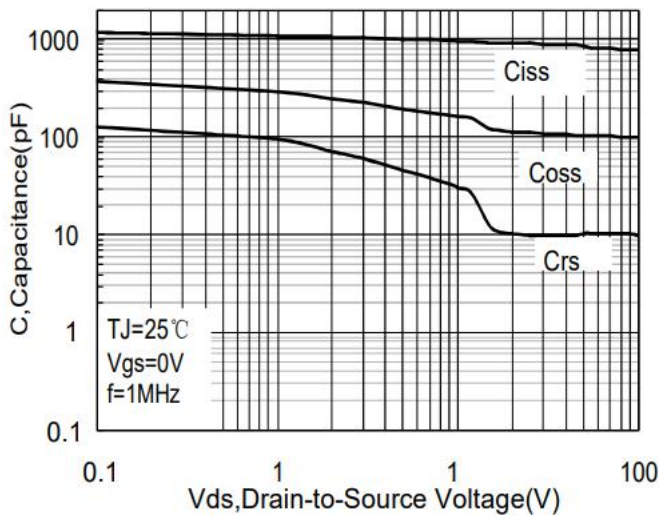
**Figure2. Typical Transfer Characteristics**



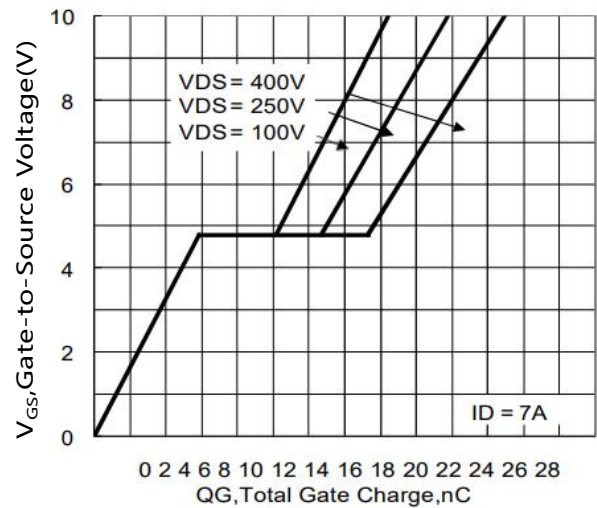
**Figure3. On-Resistance versus Drain Current**



**Figure4. Diode forward voltage versus Current**

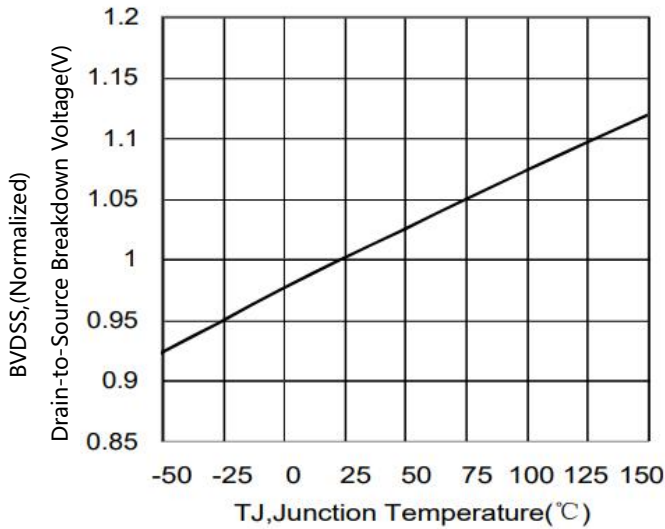


**Figure5. Typical Capacitance versus  $V_{DS}$**

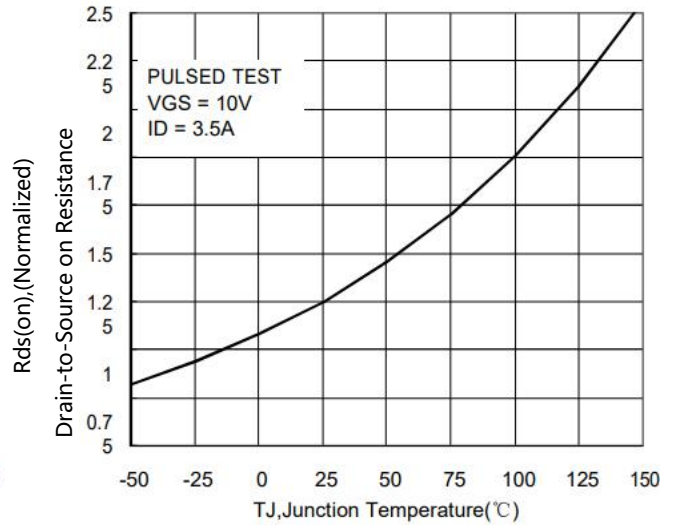


**Figure6. Typical Gate Charge versus  $V_{GS}$**

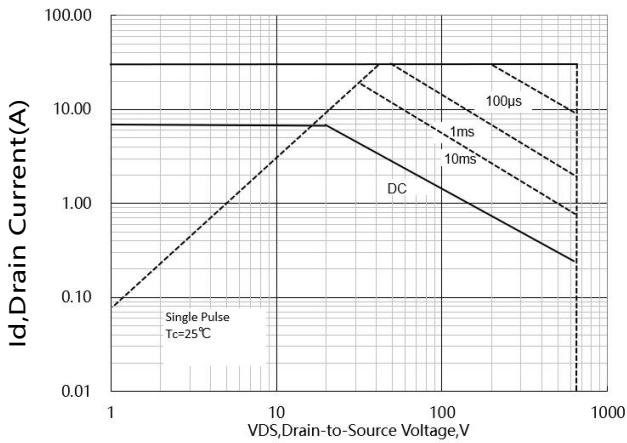
**TYPICAL CHARACTERISTICS(Cont.)**



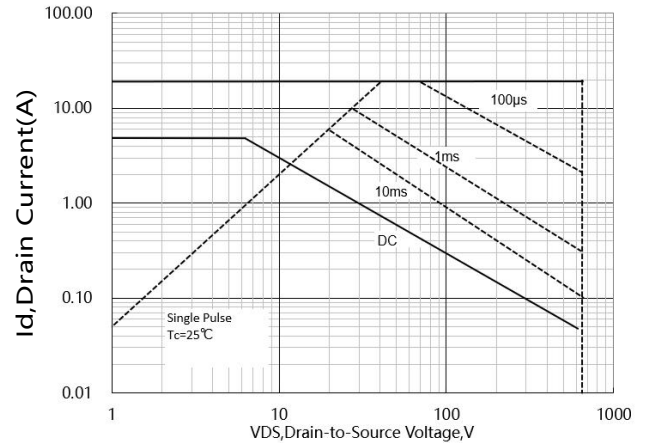
**Figure7. BV<sub>DSS</sub> Variation with Temperature**



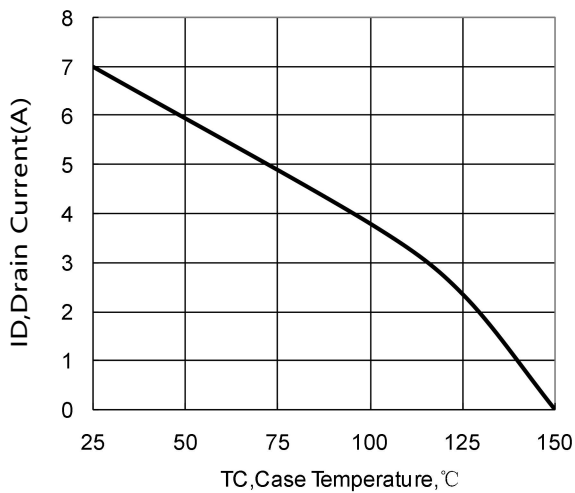
**Figure8. On-Resistance Variation with Temperature**



**Figure9. Maximum Safe Operating Area  
BXP7N65U/D/P**

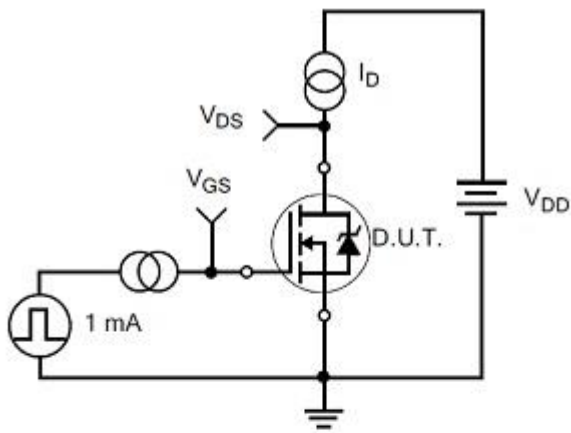


**Figure9. Maximum Safe Operating Area  
BXP7N65CF**

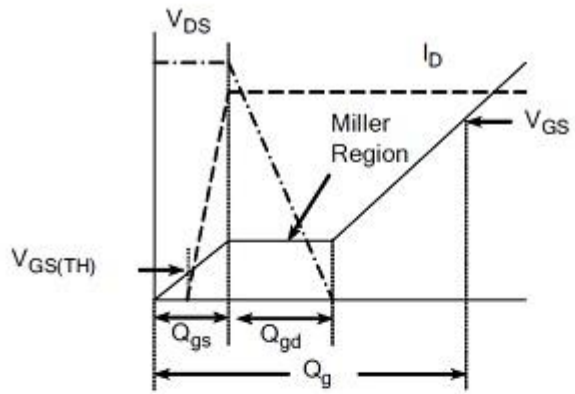


**Figure10. Maximum Continuous Drain Current  
versus Case Temperature**

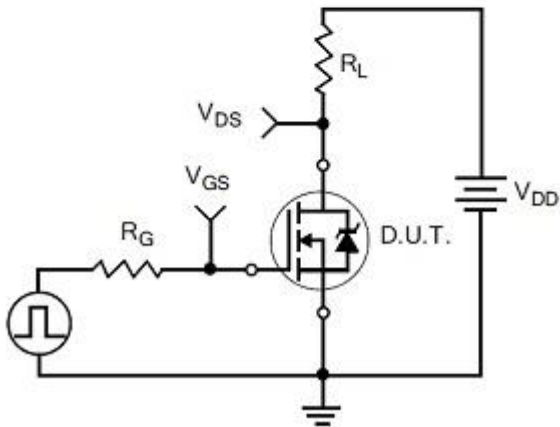
TEST CIRCUITS AND WAVEFORMS



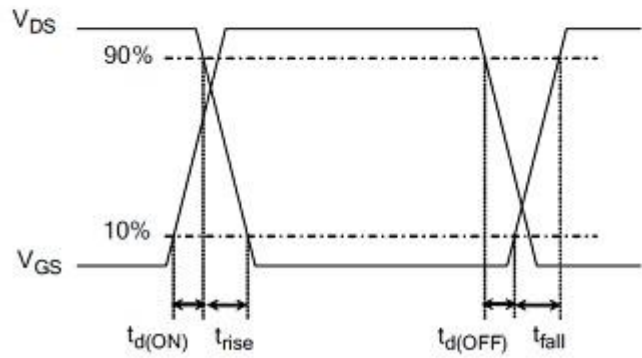
Gate Charge Test Circuit



Gate Charge Waveform

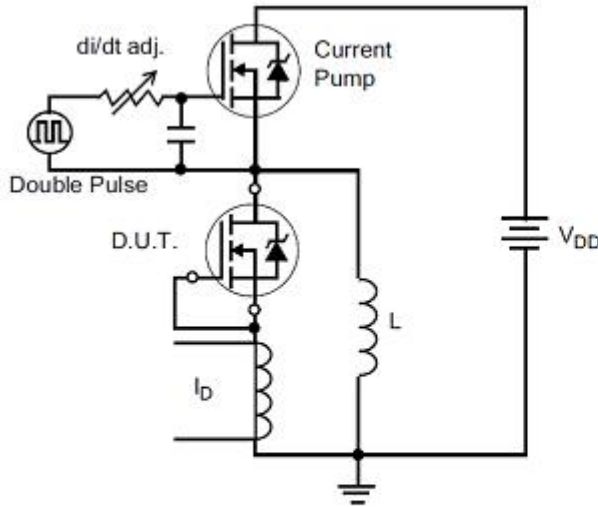


Resistive Switching Test Circuit

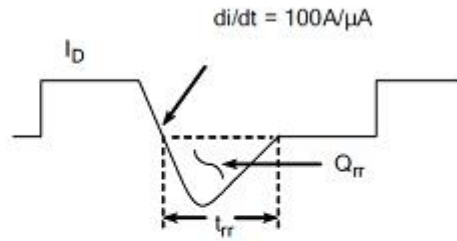


Resistive Switching Waveforms

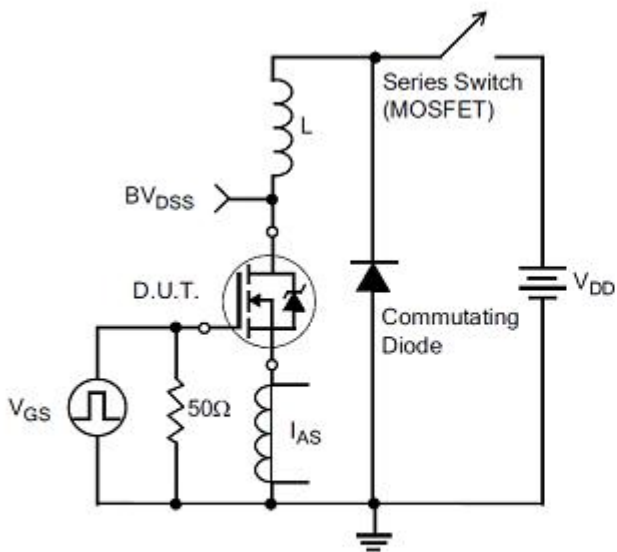
**TEST CIRCUITS AND WAVEFORMS(Cont.)**



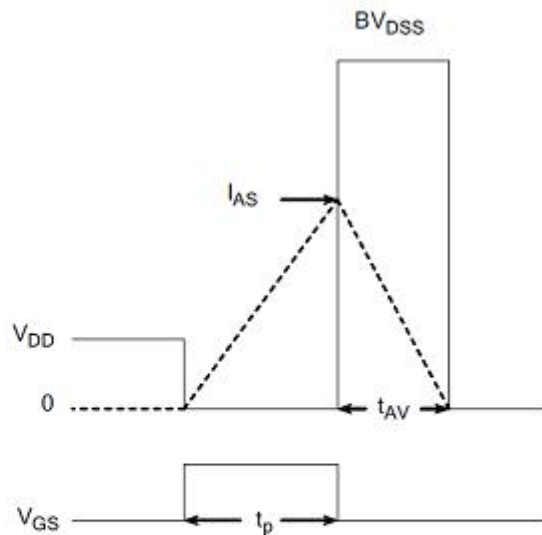
Diode Reverse Recovery Test Circuit



Diode Reverse Recovery Waveform



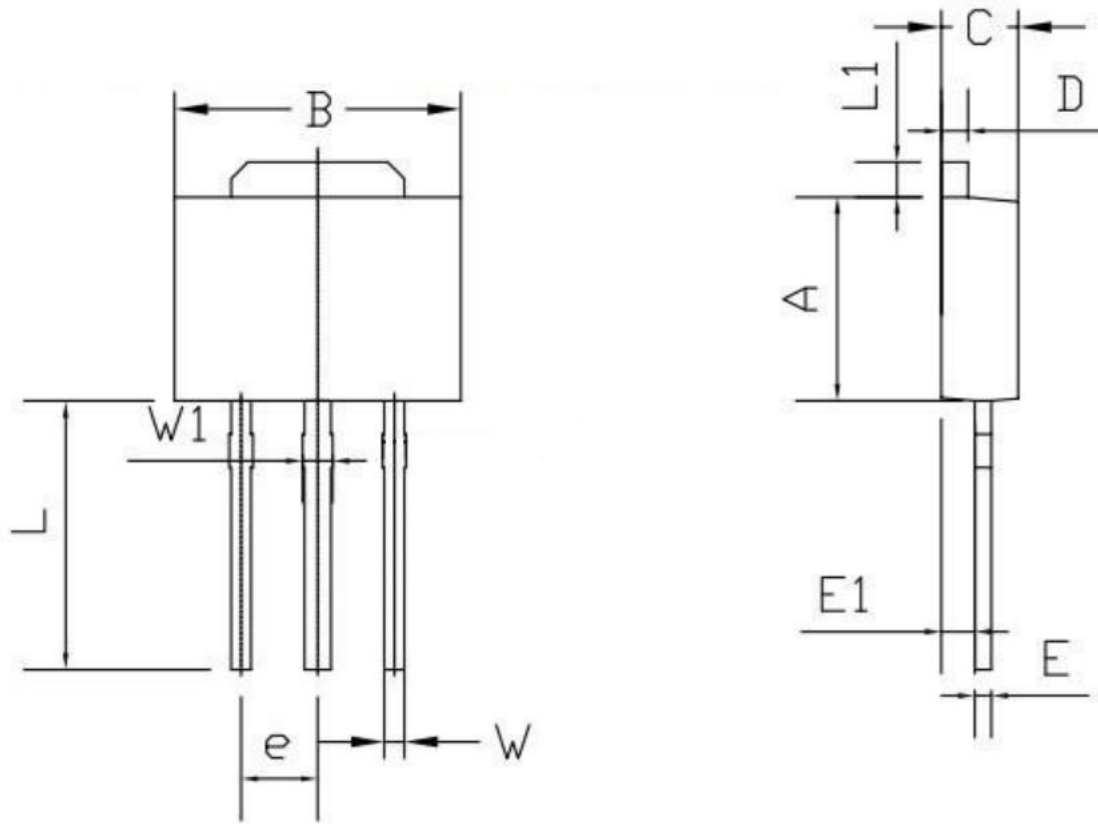
Unclamped Inductive Switching Test Circuit



$$E_{AS} = \frac{I_{AS}^2 L}{2}$$

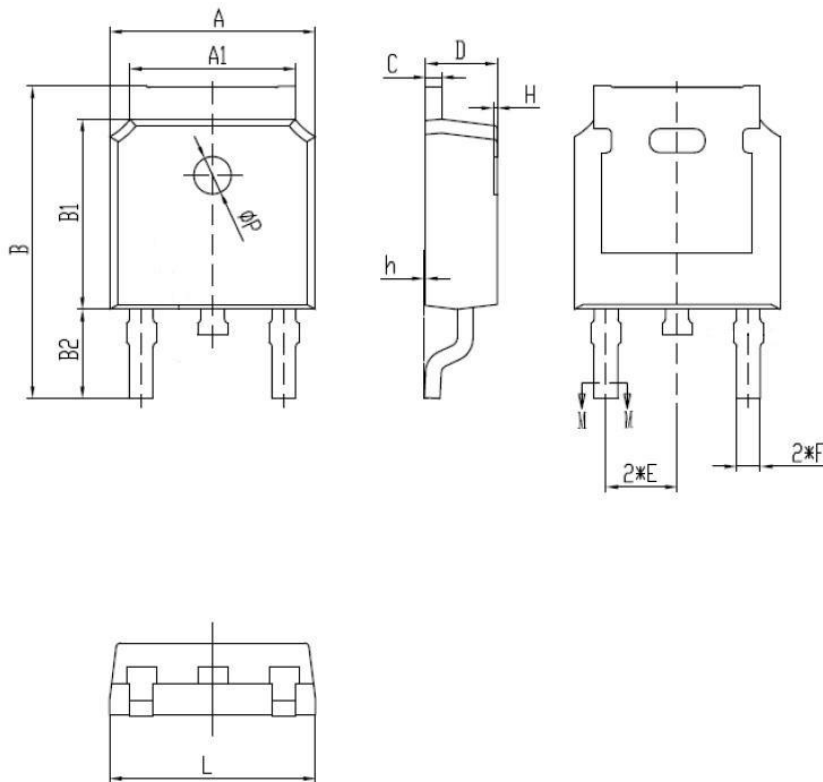
Unclamped Inductive Switching Waveforms

### TO-251 Package



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	6.00	6.20	0.235	0.245
B	6.45	6.70	0.253	0.264
C	2.05	2.55	0.080	0.101
D	0.70	0.90	0.027	0.036
E	0.49	0.53	0.019	0.021
E1	0.97	1.20	0.038	0.048
e	2.28	2.31	0.089	0.091
L	9.11	9.55	0.358	0.376
L1	0.92	1.55	0.036	0.062
W	0.65	0.95	0.025	0.038
W1	0.75	1.35	0.029	0.054

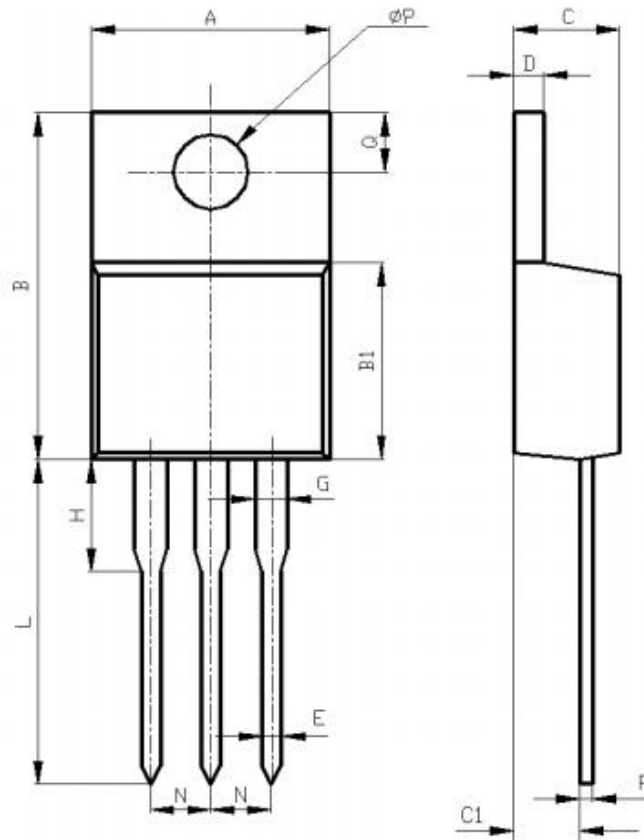
### TO-252 Package



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	6.50	6.70	0.255	0.264
A1	5.25	5.38	0.206	0.212
B	9.80	10.40	0.385	0.410
B1	6.00	6.20	0.236	0.245
B2	2.70	3.10	0.106	0.123
C	0.49	0.52	0.019	0.021
D	2.20	2.40	0.086	0.095
E	2.18	2.39	0.085	0.095
F	0.74	0.80	0.029	0.032
H	0.00	0.30	0.000	0.012
h	0.00	0.13	0.000	0.006
L	6.50	6.70	0.255	0.264
$\phi P$	1.10	1.30	0.043	0.052

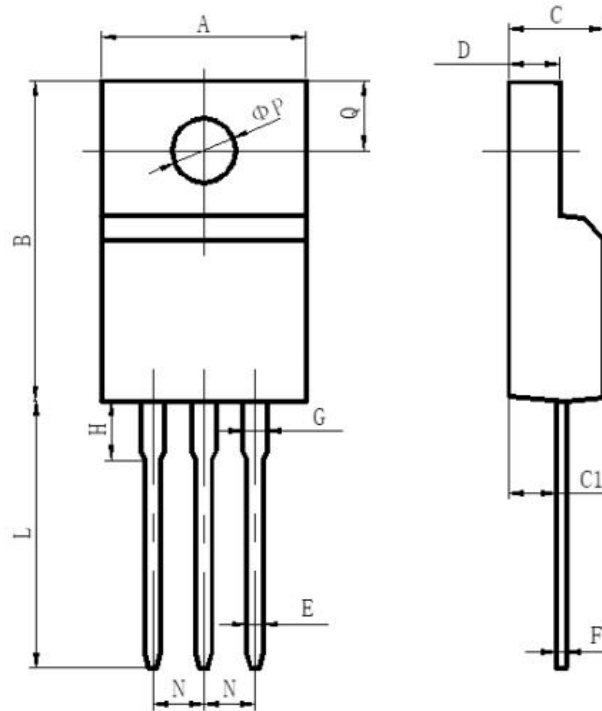


### TO-220 Package



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	9.8	10.2	0.385	0.402
B	15.4	15.8	0.606	0.623
B1	9.00	9.20	0.354	0.363
C	4.56	4.58	0.179	0.181
C1	2.35	2.45	0.092	0.097
D	1.29	1.31	0.050	0.052
E	0.77	0.83	0.030	0.033
F	0.49	0.51	0.019	0.021
G	1.25	1.29	0.049	0.051
H	2.90	3.30	0.114	0.130
L	13.35	13.65	0.525	0.538
N	2.44	2.64	0.096	0.104
Q	2.70	2.90	0.106	0.115
φP	3.59	3.69	0.141	0.146

### TO-220F Package



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	9.90	10.30	0.389	0.406
B	15.77	16.20	0.620	0.638
C	4.55	4.95	0.179	0.195
C1	2.10	2.88	0.082	0.114
D	2.40	2.80	0.094	0.111
E	0.60	1.00	0.023	0.040
F	0.42	0.58	0.016	0.023
G	1.10	1.50	0.043	0.060
H	2.90	3.50	0.114	0.138
L	12.50	13.65	0.492	0.538
N	2.30	2.70	0.090	0.107
Q	3.00	3.40	0.118	0.134
$\phi P$	3.00	3.52	0.118	0.139

## Revision history

### Document revision history

Date	Revision	Changes
18-Oct-2020	1.0	First release
9-Sep-2021	2.0	Update text formatting and other
25-Nov-2021	2.1	Add POD
19-Dec-2021	2.2	Update layout format
6-Jan-2022	2.3	Update parameter

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